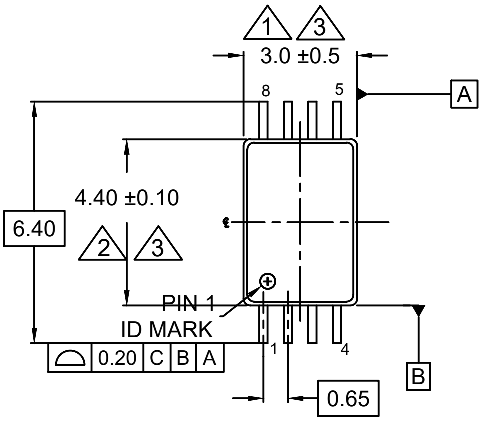
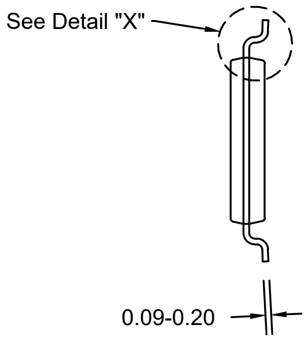
Package Outline Drawing

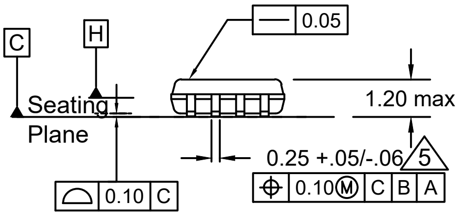
M8.173
HU0008AA
8-Lead Thin Shrink Small Outline (TSSOP) Package 3.0 x 4.40 x 1.20 mm Body, 0.65 mm Pitch
Rev. 03, Nov 20, 2025



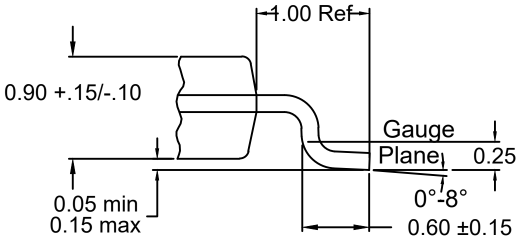
Top View



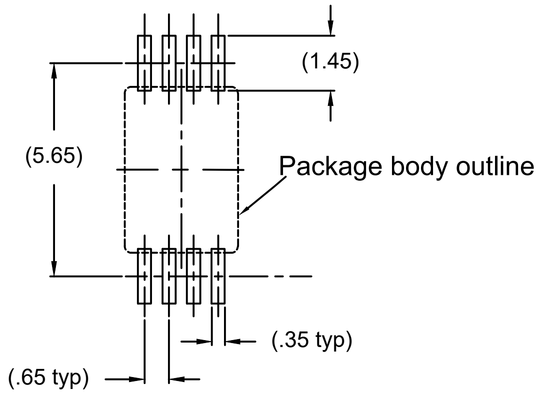
End View



Side View



Detail X



Typical Recommended Land Pattern

Notes: (all units are in mm)

(1) Dimension does not include mold flash, protrusions or gate burrs. Mold flash, protrusions or gate burrs shall not exceed 0.15 per side.
(2) Dimension does not include interlead flash or protrusion. Interlead flash or protrusion shall not exceed 0.15 per side.
(3) Dimensions are measured at datum plane H.
(4) Dimensioning and tolerancing per ASME Y14.5M-1994.
(5) Dimension on lead width does not include dambar protrusion. Allowable protrusion shall be 0.08 mm total in excess of dimension at maximum material condition. Minimum space between protrusion and adjacent lead is 0.07mm.
(6) Dimension in ( ) are for reference only.
(7) Conforms to JEDEC MO-153, variation AC. Issue E